

# INTERNATIONAL STANDARD

**IEC**  
**60191-6-13**

First edition  
2007-06

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## **Mechanical standardization of semiconductor devices –**

### **Part 6-13: Design guideline of open-top-type sockets for Fine-pitch Ball Grid Array and Fine-pitch Land Grid Array (FBGA/FLGA)**

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CH-1211 Geneva 20  
Switzerland  
Email: [inmail@iec.ch](mailto:inmail@iec.ch)  
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Commission Electrotechnique Internationale  
International Electrotechnical Commission  
Международная Электротехническая Комиссия

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## INTERNATIONAL ELECTROTECHNICAL COMMISSION

**MECHANICAL STANDARDIZATION OF SEMICONDUCTOR DEVICES –****Part 6-13: Design guideline of open-top-type sockets for Fine-pitch Ball Grid Array and Fine-pitch Land Grid Array (FBGA/FLGA)**

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International Standard IEC 60191-6-13 has been prepared by subcommittee 47D: Mechanical standardization for semiconductor devices, of IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

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Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

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